



CyberOptics® Features the New ReticleSense Airborne Particle Sensor and Announces Extension of its APS line to 150mm at SEMICON West 2014

Proven APS technology now available in multiple form factors to meet market demand

San Francisco, CA — SEMICON WEST 2014 – July 7, 2014 — [CyberOptics Corporation](#) (NASDAQ: CYBE), a world leader in intelligent inspection and sensing solutions for electronics assembly and semiconductor process equipment, will showcase its most efficient and effective wireless measurement devices for chamber gapping, leveling, wafer handoff teaching, vibration and airborne particle measurement, at [SEMICON West 2014](#) in Booth #2511 at the Moscone Center, San Francisco, July 8-10.

CyberOptics will demonstrate the newly available ReticleSense Airborne Particle Sensor (APSR) which is an extension of the wafer-shaped WaferSense Airborne Particle Sensor (APS) line that has been adopted by major semiconductor fabs and OEM equipment makers worldwide.

To address the market demand for airborne particle measurement in 150mm semiconductor and gallium arsenide (GaAs) fabs in China, Europe, Japan, the U.S. and Taiwan, as well as LED fabs, CyberOptics also announced an extension of its APS line to include a 150mm wafer form factor.

With APS technology, equipment engineers can quickly and wirelessly monitor, identify and troubleshoot airborne particles in real-time within semiconductor process equipment and automated material handling systems. WaferSense and ReticleSense Airborne Particle Sensors enable equipment engineers to shorten equipment qualification, release to production and maintenance cycles all while reducing expenses. Customers have experienced up to 88% time savings, up to 95% reduction in costs, and up to 20X the throughput with half the manpower resource requirements using the WaferSense APS relative to legacy surface scan wafer methods.

“Minimizing airborne particles in the semiconductor industry and other markets operating under stringent manufacturing quality and productivity standards is critical. CyberOptics is delivering on our customers’ needs for airborne particle measurement in various form factors that help improve fab productivity while continuing to reduce costs,” said Subodh Kulkarni, President and CEO of CyberOptics.

Semiconductor fabs and OEMs value the accuracy, precision and versatility of the specialized WaferSense and ReticleSense measurement portfolio that enables improvements in fab yields and equipment uptime.

About the WaferSense Line

The WaferSense measurement portfolio including the Auto Leveling System (ALS), the Auto Gapping System (AGS), the Auto Vibration System (AVS), the Auto Teaching System (ATS) and the Airborne Particle Sensor (APS) are available now in 150mm, 200mm, 300mm and 450mm wafer sizes. The ReticleSense Airborne Particle Sensor (APRS) and ReticleSense Auto Leveling System (ALSR) products are available in a reticle shaped form factor.

For more information about the entire line of Cyber Optics solutions please visit the company's new website at www.cyberoptics.com to find any information related to measurement device usage by fab application.

About CyberOptics

Founded in 1984, CyberOptics Corporation is a leading provider of sensors and inspection systems that provide process yield and through-put improvement solutions for the global electronic assembly and semiconductor capital equipment markets. Our products are deployed on production lines that manufacture surface mount technology circuit boards and semiconductor process equipment. Through internal development and acquisitions, CyberOptics is strategically repositioning itself to become a global leader in high-precision 3D sensors. Headquartered in Minneapolis, Minnesota, CyberOptics conducts worldwide operations through facilities in North America, Asia and Europe.

Statements regarding the Company's anticipated performance are forward-looking and therefore involve risks and uncertainties, including but not limited to: market conditions in the global SMT and semiconductor capital equipment industries; increasing price competition and price pressure on our product sales, particularly our SMT systems; the level of orders from our OEM customers; the availability of parts required for meeting customer orders; unanticipated product development challenges; the effect of world events on our sales, the majority of which are from foreign customers; product introductions and pricing by our competitors; the level of revenue and loss we record in 2014; the success of our 3D technology initiatives; expectations regarding LDI and its impact on our operations; integration risks associated with LDI and other factors set forth in the Company's filings with the Securities and Exchange Commission.

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